



 $20.32\mathrm{mm}$ (0.8") SINGLE DIGIT NUMERIC DIS-

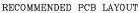
PLAY

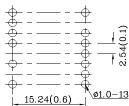
Features

- Low power consumption
- ullet Robust package
- I.C. Compatible
- Standard configuration: Gray face w/ white segments
- \bullet Optional black face provides superior color contrast
- RoHS Compliant

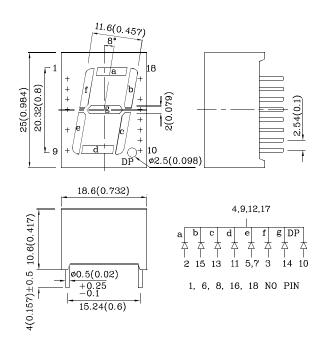








Package Schematics



Notes

1. All dimensions are in millimeters (inches), Tolerance is $\pm 0.25 (0.01")$ unless otherwise noted.

2. Specifications are subject to change without notice.

Absolute Maximum Ratings (T_A =25°C)	VG (AlGaInP)	Unit		
Reverse Voltage	$V_{\rm R}$	5	V	
Forward Current	I_{F}	30	mA	
Forward Current (Peak) 1/10 Duty Cycle 0.1ms Pulse Width	ifs	150	mA	
Power Dissipation	P_{D}	75	mW	
Operating Temperature	T_{A}	-40 ~ +85	°C	
Storage Temperature	Tstg	-40 ~ +85		
Lead Solder Temperature [2mm Below Package Base]	260°C For 3-5 Seconds			

Operating Characteristics (T _A =25°C)	VG (AlGaInP)	Unit	
Forward Voltage (Typ.) (I _F =10mA)	V_{F}	2	V
Forward Voltage (Max.) (I _F =10mA)	V_{F}	2.5	V
Reverse Current (Max.) (V _R =5V)	I_R	10	uA
Wavelength of Peak Emission CIE127-2007* (Typ.) (I _F =10mA)	λP	574*	nm
Wavelength of Dominant Emission CIE127-2007* (Typ.) (I _F =10mA)	λD	570*	nm
Spectral Line Full Width At Half-Maximum (Typ.) (I _F =10mA)	$\triangle \lambda$	20	nm
Capacitance (Typ.) (V _F =0V, f=1MHz)	С	15	pF

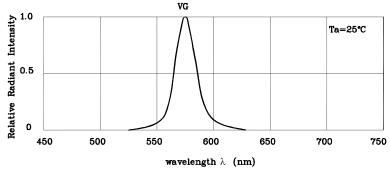
Part Number	Emitting Color	Emitting Material	Luminous Intensity CIE127-2007* (I _F =10mA) ucd		Wavelength CIE127- 2007* nm λP	Description
			min.	typ.		
XDVG20C-1	Green	AlGaInP	14000 3600*	24990 8690*	574*	Common Cathode, Rt. Hand Decimal

 $^{{\}rm ^*Luminous\ intensity\ value\ and\ wavelength\ are\ in\ accordance\ with\ CIE127-2007\ standards.}$

Jan 18,2014 XDSB7706 V1-X Layout: Maggie L.

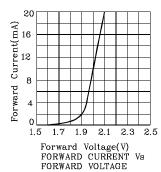
www.SunLEDusa.com

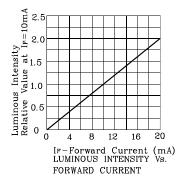


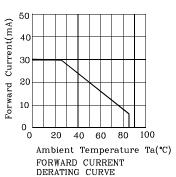


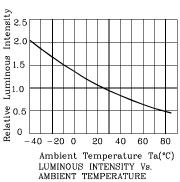
RELATIVE INTENSITY Vs. CIE WAVELENGTH

♦ VG

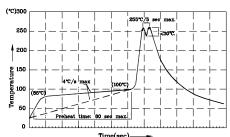








Wave Soldering Profile for Thru-Hole Products (Pb-Free Components)



- nmend pre-heat temperature of 105°C or less (as measured with a noccouple attached to the LED pins) prior to immersion in the solder with a maximum solder bath temperature of 250°C wave soldering temperature between 245°C \sim 255°C for 3 sec (5 sec
- 2.Peak wave soldering temperature oetwermax).
 3.Do not apply stress to the epoxy resin (-Pixtures should not incur stress on the during soldering process.
 5.SAC 305 solder alloy is recommended.
 6.No more than one wave soldering pass.

Remarks:

If special sorting is required (e.g. binning based on forward voltage, luminous intensity / luminous flux, or wavelength),

the typical accuracy of the sorting process is as follows:

- 1. Wavelength: +/-1nm
- 2. Luminous Intensity / Luminous Flux: +/-15%
- 3. Forward Voltage: +/-0.1V

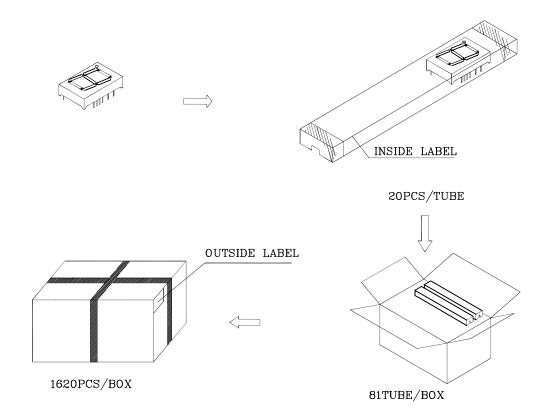
Note: Accuracy may depend on the sorting parameters.

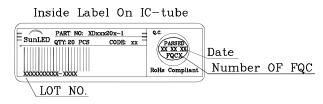


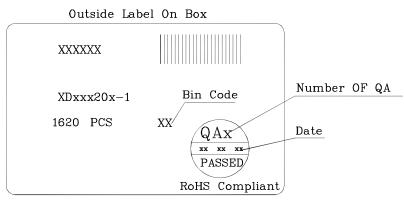
 $20.32\mathrm{mm}$ (0.8") SINGLE DIGIT NUMERIC DIS-

PLAY

PACKING & LABEL SPECIFICATIONS







TERMS OF USE

- 1. Data presented in this document reflect statistical figures and should be treated as technical reference only.
- 2. Contents within this document are subject to improvement and enhancement changes without notice.
- 3. The product(s) in this document are designed to be operated within the electrical and environmental specifications indicated on the datasheet. User accepts full risk and responsibility when operating the product(s) beyond their intended specifications.
- 4. The product(s) described in this document are intended for electronic applications in which a person's life is not reliant upon the LED. Please consult with a SunLED representative for special applications where the LED may have a direct impact on a person's life.
- 5. The contents within this document may not be altered without prior consent by SunLED.
- 6. Additional technical notes are available at http://www.SunLEDusa.com/TechnicalNotes.asp

Jan 18,2014